

# AP1203AGMT-HF

**Halogen-Free Product**

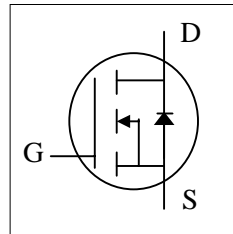


**Advanced Power  
Electronics Corp.**

*N-CHANNEL ENHANCEMENT MODE*

*POWER MOSFET*

- ▼ Simple Drive Requirement
- ▼ SO-8 Compatible with Heatsink
- ▼ Low On-resistance
- ▼ RoHS Compliant

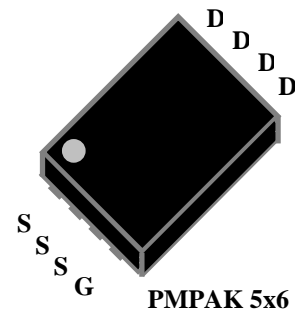


$BV_{DSS}$	30V
$R_{DS(ON)}$	12m $\Omega$
$I_D$	37A

## Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The PMPAK 5x6 package is special for DC-DC converters application and the foot print is compatible with SO-8 with backside heat sink and lower profile.



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	+20	V
$I_D@T_C=25^\circ\text{C}$	Continuous Drain Current (Chip)	37	A
$I_D@T_A=25^\circ\text{C}$	Continuous Drain Current <sup>3</sup>	15.8	A
$I_D@T_A=70^\circ\text{C}$	Continuous Drain Current <sup>3</sup>	12.6	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	150	A
$P_D@T_C=25^\circ\text{C}$	Total Power Dissipation	27.8	W
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation	5	W
$E_{AS}$	Single Pulse Avalanche Energy <sup>4</sup>	16.2	mJ
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

## Thermal Data

Symbol	Parameter	Value	Units
Rthj-c	Maximum Thermal Resistance, Junction-case	4.5	$^\circ\text{C}/\text{W}$
Rthj-a	Maximum Thermal Resistance, Junction-ambient <sup>3</sup>	25	$^\circ\text{C}/\text{W}$



# AP1203AGMT-HF

## Electrical Characteristics @T<sub>j</sub>=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	30	-	-	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	-	12	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A	-	-	22	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	1	-	3	V
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =20A	-	27	-	S
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V	-	-	10	uA
I <sub>GSS</sub>	Gate-Source Leakage	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
Q <sub>g</sub>	Total Gate Charge <sup>2</sup>	I <sub>D</sub> =20A	-	6	9.6	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =15V	-	1.7	-	nC
Q <sub>gd</sub>	Gate-Drain ("Miller") Charge	V <sub>GS</sub> =4.5V	-	3.6	-	nC
t <sub>d(on)</sub>	Turn-on Delay Time <sup>2</sup>	V <sub>DS</sub> =15V	-	6	-	ns
t <sub>r</sub>	Rise Time	I <sub>D</sub> =1A	-	7.5	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time	R <sub>G</sub> =3.3Ω, V <sub>GS</sub> =10V	-	16.5	-	ns
t <sub>f</sub>	Fall Time	R <sub>D</sub> =15Ω	-	6	-	ns
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V	-	420	670	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =25V	-	130	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	f=1.0MHz	-	75	-	pF
R <sub>g</sub>	Gate Resistance	f=1.0MHz	-	3.3	5	Ω

## Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V <sub>SD</sub>	Forward On Voltage <sup>2</sup>	I <sub>S</sub> =20A, V <sub>GS</sub> =0V	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time <sup>2</sup>	I <sub>S</sub> =10A, V <sub>GS</sub> =0V,	-	19	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI/dt=100A/μs	-	10	-	nC

### Notes:

- 1.Pulse width limited by Max. junction temperature
- 2.Pulse test
- 3.Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board, t ≤10sec, 60°C/W at steady state.
- 4.Starting T<sub>j</sub>=25°C , V<sub>DD</sub>=25V , L=0.1mH , R<sub>G</sub>=25Ω , I<sub>AS</sub>=18A.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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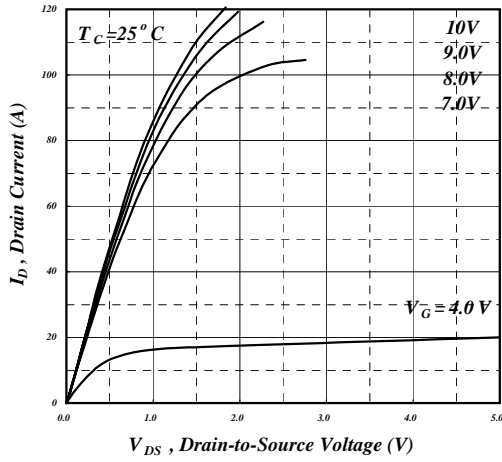


Fig 1. Typical Output Characteristics

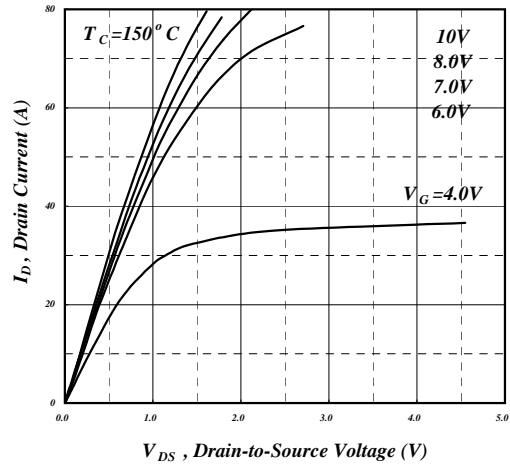


Fig 2. Typical Output Characteristics

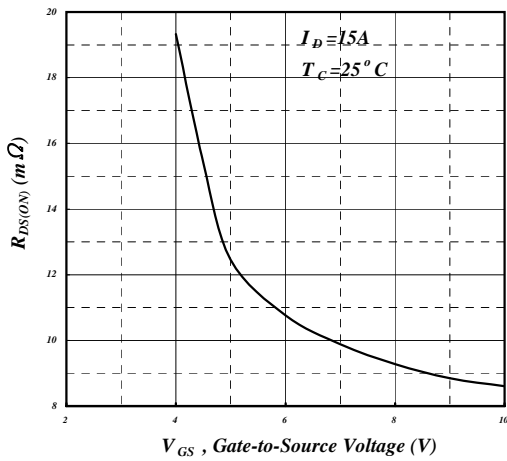


Fig 3. On-Resistance v.s. Gate Voltage

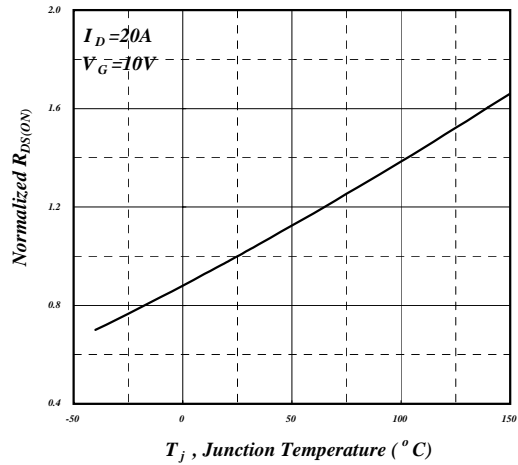


Fig 4. Normalized On-Resistance v.s. Junction Temperature

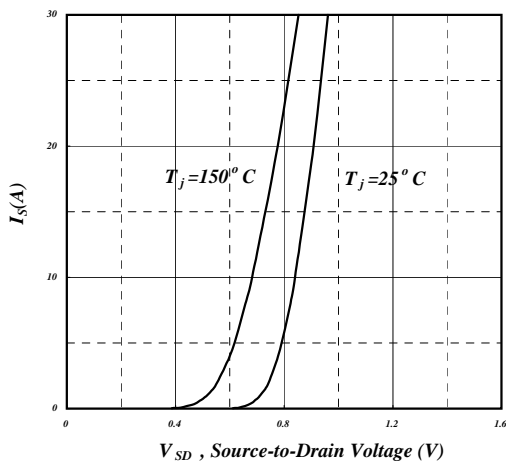


Fig 5. Forward Characteristic of Reverse Diode

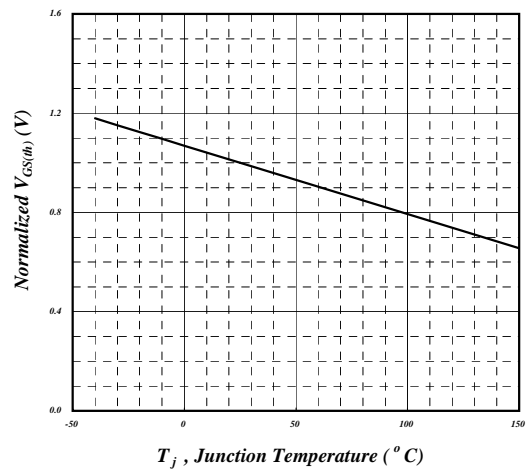
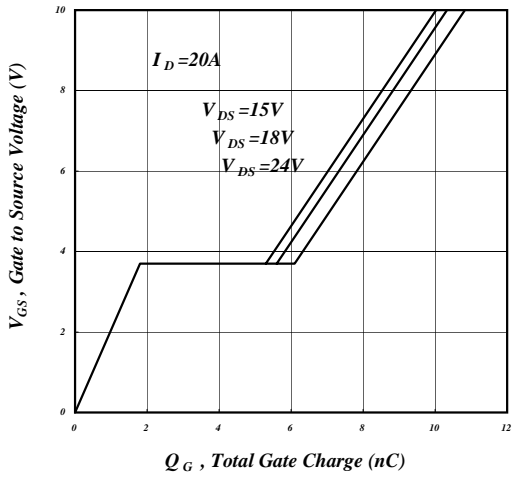
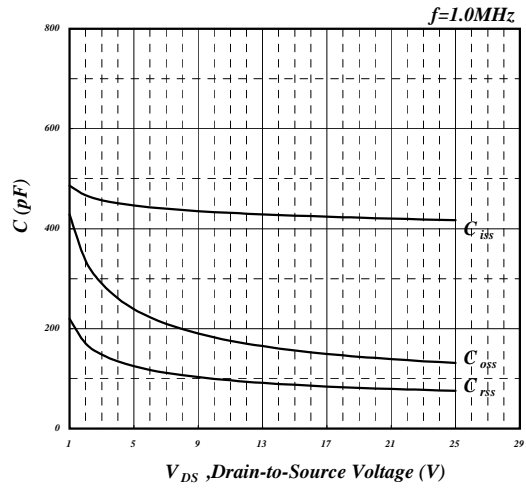


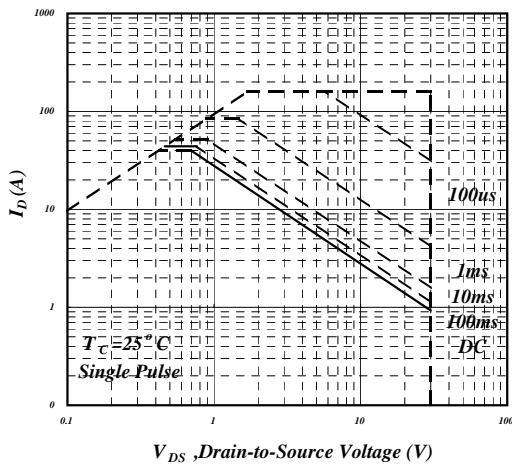
Fig 6. Gate Threshold Voltage v.s. Junction Temperature



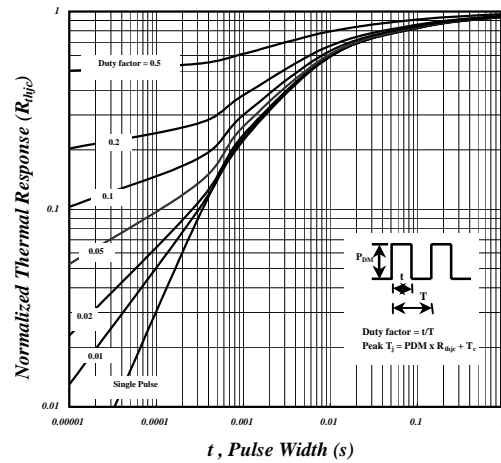
**Fig 7. Gate Charge Characteristics**



**Fig 8. Typical Capacitance Characteristics**



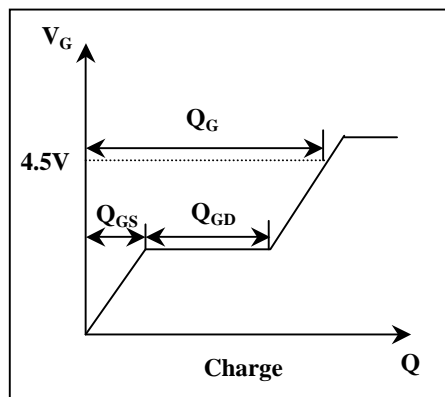
**Fig 9. Maximum Safe Operating Area**



**Fig 10. Effective Transient Thermal Impedance**



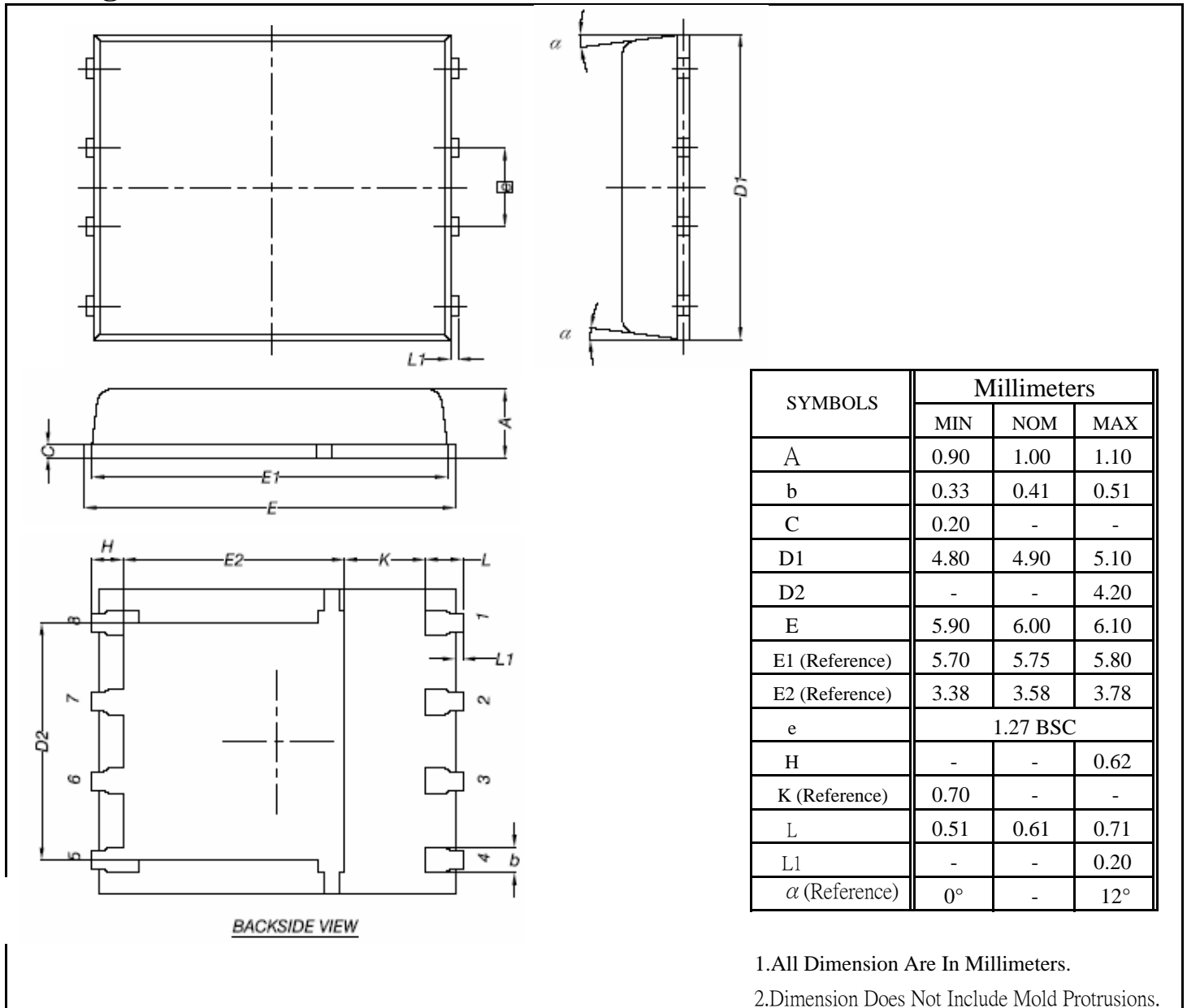
**Fig 11. Switching Time Waveform**



**Fig 12. Gate Charge Waveform**



Package Outline : PMPAK 5x6



Part Marking Information & Packing : PMPAK 5x6

